









LM2901-Q1, LM2901V-Q1, LM2901AV-Q1 SLCS142F - DECEMBER 2003 - REVISED MAY 2021

LM2901x-Q1 Quadruple Automotive Comparator

1 Features

- Qualified for automotive applications
- AEC-Q100 Qualified with the following results:
 - Device temperature grade 1: –40°C to 125°C ambient operating temperature range
 - Device HBM ESD classification levels:
 - H1B for "AV" version
 - H1C for all other versions
 - Device CDM ESD classification level C6
- Single supply or dual supplies
- Low supply-current drain independent of supply voltage 0.8mA (typical)
- Low input bias current 25 nA (typical)
- Low input offset current 2 nA (typical)
- Low input offset voltage 2mV Typ (typical)
- Common-mode input voltage range includes around
- Differential input voltage range equal to maximumrated supply voltage ±36 V
- Low output saturation voltage
- Output compatible with TTL, MOS, and CMOS
- For single version in 5-pin SOT-23, see the TL331-Q1 (SLVS969)

2 Applications

- **Automotive**
 - HEV/EV and power train
 - Infotainment and cluster
 - Body control module
- Industrial
- **Appliances**

3 Description

The LM2901x-Q1 family of devices consists of four independent voltage comparators, designed to operate from a single power supply over a wide range of voltages.

Operation from dual supplies is possible, provided the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage.

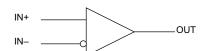
The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

LM2901V-Q1 supports higher 32 V supply voltage and LM2901AV-Q1 supports the higher 32 V supply voltage and lower offset voltage.

Device Information

PART NUMBER	PACKAGE (1)	BODY SIZE (NOM)
LM2901-Q1	TSSOP (14)	4.40 mm × 5.00 mm
LM2901A-Q1 LM2901AV-Q1	SOIC (14)	3.91 mm × 8.65 mm

For all available packages, see the orderable addendum at the end of the data sheet.



Copyright © 2016, Texas Instruments Incorporated

Simplified Schematic



Table of Contents

14	D.O O.		
1 Features	1	7.4 Device Functional Modes	8
2 Applications	1	8 Application and Implementation	<mark>9</mark>
3 Description	1	8.1 Application Information	
4 Revision History	2	8.2 Typical Application	ç
5 Pin Configuration and Functions	3	9 Power Supply Recommendations	11
6 Specifications	4	10 Layout	<u>1</u> 1
6.1 Absolute Maximum Ratings	4	10.1 Layout Guidelines	<mark>11</mark>
6.2 ESD Ratings		10.2 Layout Example	11
6.3 Recommended Operating Conditions	4	11 Device and Documentation Support	12
6.4 Thermal Information	<mark>5</mark>	11.1 Documentation Support	12
6.5 Electrical Characteristics LM2901x-Q1	6	11.2 Related Links	
6.6 Switching Characteristics LM2901x-Q1	6	11.3 Trademarks	12
6.7 Typical Characteristics LM2901x-Q1		11.4 Electrostatic Discharge Caution	12
7 Detailed Description	8	11.5 Glossary	12
7.1 Overview	8	12 Mechanical, Packaging, and Orderable	
7.2 Functional Block Diagram	8	Information	12
7.3 Feature Description			
4 Revision History	Poviolor	a E (May 2024)	Dogg
Changes from Revision E (January 2015) to F			Page
 Updated Front Page HBM ESD Classification 			
 Updated the numbering format for tables, figure 	ures, and	d cross-references throughout the document	1
 Added seporate line for 1kV LM2901AV-Q1 F 	HBM in E	SD Ratings table	4
 Changed incorrect text in Apps Section Feature 	ure Desc	cription	8
Changes from Revision D (April 2008) to Rev	ision E	(January 2015)	Page

•	Added AEC-Q100 results to the Features section
•	Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and
	Implementation section, Power Supply Recommendations section, Layout section, Device and
	Documentation Support section, and Mechanical, Packaging, and Orderable Information section
	Added the common-mode voltage note to the V _{ICD} parameter in the <i>Flectrical Characteristics</i> table



5 Pin Configuration and Functions

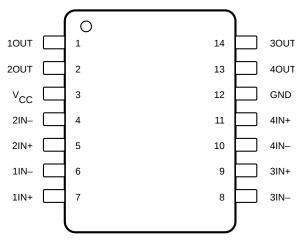


Figure 5-1. D and PW Packages 14-Pin SOIC and TSSOP Top View

Table 5-1. Pin Functions

	PIN I/		DESCRIPTION
NO.	NAME	- I/O	DESCRIPTION
1	10UT	0	Output of comparator 1
2	2OUT	0	Output of comparator 2
3	V _{CC}	_	Supply Pin
4	2IN-	I	Negative input of comparator 2
5	2IN+	I	Positive input of comparator 2
6	1IN-	ı	Negative input of comparator 1
7	1IN+	I	Positive input of comparator 1
8	3IN-	I	Negative input of comparator 3
9	3IN+	I	Positive input of comparator 3
10	4IN-	I	Negative input of comparator 4
11	4IN+	ı	Positive input of comparator 4
12	GND	_	Ground
13	4OUT	0	Output of comparator 4
14	3OUT	0	Output of comparator 3



6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

	MIN	MAX	UNIT	
Supply voltage, V _{CC} ⁽²⁾		36		
Differential input voltage, V _{ID} ⁽³⁾		±36		
Input voltage range, V _I (either input)	-0.3			
Output voltage, V _O		36		
Output current, I _O		20	mA	
Duration of output short circuit to ground ⁽⁴⁾	Unlimited			
Operating virtual junction temperature, T _J		150	°C	
Storage temperature, T _{stg}	-65	150	°C	

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) All voltage values, except differential voltages, are with respect to network ground.
- 3) Differential voltages are at IN+ with respect to IN-.
- (4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.

6.2 ESD Ratings

			MIN	MAX	UNIT
		Human-body model (HBM), per AEC Q100-002 ⁽¹⁾ , (LM2901-Q1, LM2901V-Q1)	-2000	2000	
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 ⁽¹⁾ , (LM2901AV-Q1 Only)	-1000	1000	V
		Charged-device model (CDM), per AEC Q100-011	-1000	1000	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V _{CC}	Cumply voltage	LM2901-Q1	2	30	\/	
	Supply voltage	LM2901V-Q1, LM2901AV-Q1	2	32	7 V	
T _A	Ambient temperature	Ambient temperature				
Io	Output current (per comparator)		0	4	mA	



6.4 Thermal Information

		LM2901x-Q1			
	THERMAL METRIC ⁽¹⁾	D (SOIC)	PW (TSSOP)	UNIT	
		14 PINS	14 PINS		
R _{0JA}	Junction-to-ambient thermal resistance ⁽²⁾	88.6	119.1	°C/W	
R ₀ JC(top)	Junction-to-case (top) thermal resistance	49.1	47.9	°C/W	
$R_{\theta JB}$	Junction-to-board thermal resistance	43.0	60.9	°C/W	
ΨЈТ	Junction-to-top characterization parameter	13.6	5.4	°C/W	
ΨЈВ	Junction-to-board characterization parameter	42.7	60.3	°C/W	

⁽¹⁾ For more information about traditional and new thermal metrics, see the Semicondctor and IC Package Thermal Metrics application report, SPRA953.

⁽²⁾ Maximum power dissipation is a function of $T_{J(max)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_{J(max)} - T_A) / R_{\theta JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.



6.5 Electrical Characteristics LM2901x-Q1

V_{CC} = 5 V, at specified free-air temperature (unless otherwise noted)

	PARAMETER	TEST CO	ONDITIONS ⁽¹⁾	T _A (2)	MIN	TYP	MAX	UNIT	
		V V	Non A devices	25°C		2	7		
\/	Input offset voltage	$V_{IC} = V_{ICR(min)},$ $V_{O} = 1.4 \text{ V},$	Non A devices	Full range			15	mV	
V_{IO}	input onset voltage	$V_{CC} = 5 \text{ V to}$ $MAX^{(3)}$	A suffix devices	25°C		1	2	IIIV	
		IVIAX	A sullix devices	Full range			4		
	Input offset current	V _O = 1.4 V		25°C		5	50	nA	
I _{IO}	input onset current	V _O = 1.4 V		Full range			200	ПА	
	Input bias current	V _O = 1.4 V		25°C		-25	-250	nΛ	
I _{IB}	input bias current	V _O = 1.4 V		Full range			-500	- nA	
\/	Common-mode input-			25°C	0		V _{CC} - 1.5	V	
V_{ICR}	voltage range ⁽⁴⁾			Full range	0		V _{CC} - 2	V	
A _{VD}	Large-signal differential- voltage amplification	V_{CC} = 15 V, V_{O} = 1.4 V to 11.4 R_{L} ≥ 15 kΩ to V_{CC}	·	25°C	25	100		V/mV	
	High-level output current	\/ - 1\/	V _{OH} = 5 V	25°C		0.1	50	nA	
I _{OH}	nigri-level output current	V _{ID} – I V	$V_{OH} = V_{CC} MAX^{(3)}$	Full range			1	μA	
\/	Low lovel output voltage	V _{ID} = -1 V	l = 4 mΛ	25°C		150	400	m\/	
V_{OL}	Low-level output voltage	VIDI V	I _{OL} = 4 mA	Full range			700	mV	
I _{OL}	Low-level output current	V _{ID} = -1 V	V _{OL} = 1.5 V	25°C	6	16			
	Supply current (four	V _O = 2.5 V, No	V _{CC} = 5 V	_25°C _		0.8	2	mA	
I _{CC}	comparators)	load	$V_{CC} = MAX^{(3)}$			1	2.5		

- (1) All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
- (2) Full range (MIN to MAX) is −40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
- (3) V_{CC} MAX = 30 V for non-V devices and 32 V for V-suffix devices.
- (4) The voltage at either the input or common mode should not be allowed to negative by more that 0.3 V. The upper end of the common-mode voltage range is V_{CC+} 1.5 V; however, one input can exceed V_{CC}, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to 30 V without damage.

6.6 Switching Characteristics LM2901x-Q1

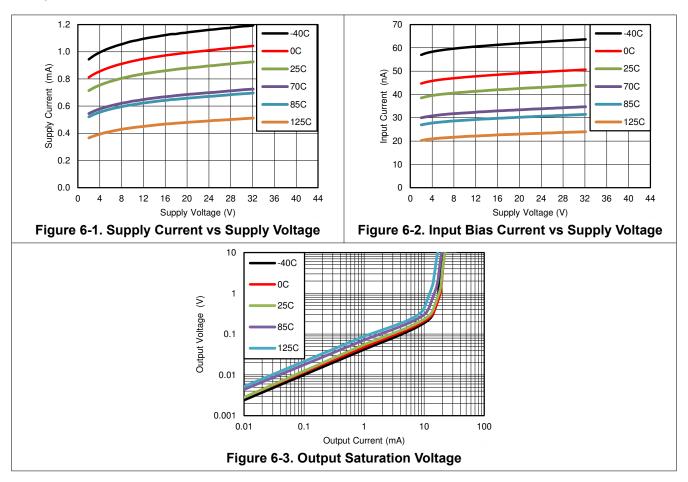
 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDI	MIN	TYP	MAX	UNIT	
Response time ⁽²⁾	R _L connected to 5 V through 5.1 kΩ, C ₁ = 15 pF ⁽¹⁾	100-mV input step with 5-mV overdrive		1.3		μs
		TTL-level input step		0.3		

- (1) C₁ includes probe and jig capacitance.
- (2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



6.7 Typical Characteristics LM2901x-Q1





7 Detailed Description

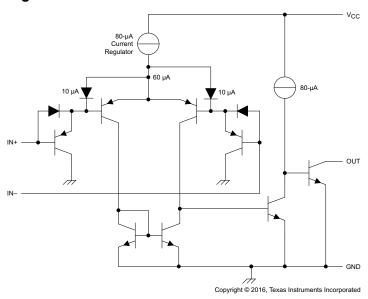
7.1 Overview

The LM2901x-Q1 family of devices is a quad comparator with the ability to operate up to an absolute maximum of 36 V on the supply pin. This standard device has proven ubiquity and versatility across a wide range of applications because of the very wide supply voltage range (2 V to 30 V or 32 V), low I_Q , and fast response of the device.

This device is AEC-Q100 qualified and can operate over a wide temperature range (-40°C to 125°C).

The open-collector output allows the user to configure the logic-high voltage of the output (V_{OH}) independent of V_{CC} and can be used with multiple comparators in wired AND functionality.

7.2 Functional Block Diagram



7.3 Feature Description

The LM2901x-Q1 family of devices consists of a PNP Darlington pair input, allowing the device to operate with very high gain and fast response with minimal input bias current. The input Darlington pair creates a limit on the input common-mode voltage ability, allowing the LM2901x-Q1 family of devices to accurately function from ground to $V_{CC}-2$ V for the lower voltage input. The higher voltage input may go up to the maximum V_{CC} . This ability enables a wide input range even when using modern-day supplies of 3.3 V and 5 V.

The output consists of an open collector bipolar transistor. The transistor sinks current when the negative input voltage is higher than the positive input voltage and the offset voltage. The V_{OL} is resistive and scales with the output current. See Figure 6-3 in Section 6.7 for the V_{OL} values with respect to the output current.

The special pinout of this device separates input pins from the output pins to reduce parasitic coupling between input and output.

7.4 Device Functional Modes

7.4.1 Voltage Comparison

The LM2901x-Q1 family of devices operates solely as a voltage comparator, comparing the differential voltage between the positive and negative pins and outputs a logic low or high impedance (logic high with pullup) based on the input differential polarity.



8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LM2901x-Q1 family of devices is typically used to compare a single signal to a reference or two signals against each other. Many users take advantage of the open-drain output to drive the comparison logic output to a logic voltage level to an MCU or logic device. The wide supply range and high voltage capability makes the LM2901x-Q1 family of devices optimal for level shifting to a higher or lower voltage.

8.2 Typical Application

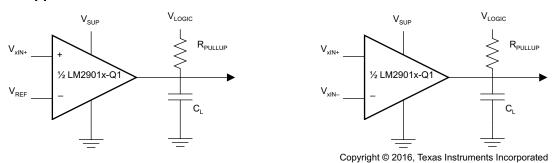


Figure 8-1. Single-Ended and Differential Comparator Configurations

8.2.1 Design Requirements

For this design example, use the parameters listed in Table 8-1 as the input parameters.

PARAMETER EXAMPLE VALUE Input voltage range 0 V to $V_{SUP} - 1.5 V$ 2 V to 36 V Supply voltage 2 V to 36 V Logic supply voltage Output current (R_{PULLUP}) 1 µA to 20 mA 100 mV Input overdrive voltage 2.5 V Reference voltage 15 pF Load capacitance (C_L)

Table 8-1. Design Parameters

8.2.2 Detailed Design Procedure

8.2.2.1 Input Voltage Range

When selecting the input voltage range, the input common-mode voltage range (V_{ICR}) must be considered. If temperature operation is above or below 25°C the V_{ICR} can range from 0 V to $V_{CC}-2$ V. The V_{ICR} range limits the input voltage range to as high as $V_{CC}-2$ V and as low as 0 V. Operation outside of this range can yield incorrect comparisons.

The following lists some input voltage scenarios and the resulting outcomes:

- When both IN– and IN+ are both within the common-mode range:
 - If IN- is higher than IN+ and the offset voltage, then the output is low and the output transistor is sinking current.



- If IN- is lower than IN+ and the offset voltage, then the output is in high impedance and the output transistor is not conducting.
- When IN– is higher than common-mode and IN+ is within common-mode, the output is low and the output transistor is sinking current.
- When IN+ is higher than common-mode and IN– is within common-mode, then the output is in high impedance and the output transistor is not conducting.
- When IN– and IN+ are both higher than common-mode, then the output is low and the output transistor is sinking current.

8.2.2.2 Minimum Overdrive Voltage

The overdrive voltage is the differential voltage produced between the positive and negative inputs of the comparator over the offset voltage (V_{IO}). To make an accurate comparison the overdrive voltage (V_{OD}) must be higher than the input offset voltage (V_{IO}). The overdrive voltage can also determine the response time of the comparator, with the response time decreasing as the overdrive increases. Figure 8-2 and Figure 8-3 show positive and negative response times with respect to overdrive voltage.

8.2.2.3 Output and Drive Current

Output current is determined by the load or pullup resistance and logic or pullup voltage. The output current produces an output low voltage (V_{OL}) from the comparator. In which V_{OL} is proportional to the output current. Use Figure 6-3 to determine V_{OL} based on the output current.

The output current can also effect the transient response. See Section 8.2.2.4 for more information.

8.2.2.4 Response Time

The transient response can be determined by the load capacitance (C_L), load or pullup resistance (R_{PULLUP}), and equivalent collector-emitter resistance (R_{CF}).

Use Equation 1 and Equation 2 to calculate the approximate values of the rise time (t_r) and fall time (t_f).

$$t_{P} \approx R_{PULLUP} \times C_{L} \tag{1}$$

$$t_{N} \approx R_{CE} \times C_{L} \tag{2}$$

To find the value of R_{CE} , use the slope of Figure 6-3 in the linear region at the desired temperature, or divide V_{OL} by I_{O} .

8.2.3 Application Curves

The following curves were generated with 5 V on V_{CC} and V_{LOGIC} , R_{PULLUP} = 5.1 k Ω , and 50-pF scope probe.

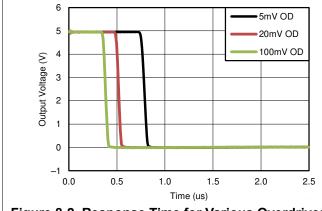


Figure 8-2. Response Time for Various Overdrives
Negative Transition

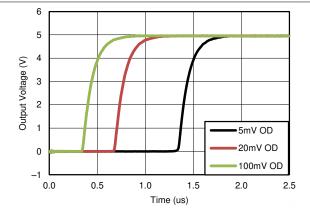


Figure 8-3. Response Time for Various Overdrives
Positive Transition



9 Power Supply Recommendations

For fast response and comparison applications with noisy or AC inputs, TI recommends using a bypass capacitor on the supply pin to reject any variation on the supply voltage. This variation can take away from some of the input common mode range of the comparator and create an inaccurate comparison.

10 Layout

10.1 Layout Guidelines

For accurate comparator applications without hysteresis, maintaining a stable power supply with minimized noise and glitches, which can affect the high-level input common-mode voltage range, is important. To achieve a stable power supply, place a bypass capacitor between the positive and negative (if available) supply voltage and ground. If a negative supply is not being used, do not put a capacitor between the GND pin of the IC and system ground.

10.2 Layout Example

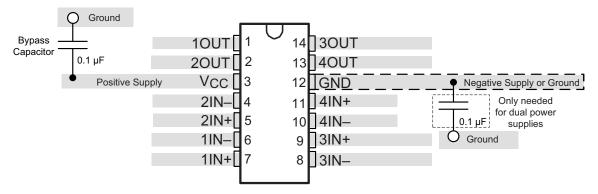


Figure 10-1. LM2901x-Q1 Layout Example



11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

For related documentation, see the following:

TL331-Q1 Single Differential Comparator, SLVS969

11.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 11-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
LM2901-Q1	Click here	Click here	Click here	Click here	Click here
LM2901V-Q1	Click here	Click here	Click here	Click here	Click here
LM2901AV-Q1	Click here	Click here	Click here	Click here	Click here
LM2901B-Q1	Click here	Click here	Click here	Click here	Click here

11.3 Trademarks

All trademarks are the property of their respective owners.

11.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.5 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

www.ti.com 28-Apr-2021

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM2901AVQDRG4Q1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901AVQ	Samples
LM2901AVQDRQ1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901AVQ	Samples
LM2901AVQPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901AVQ	Samples
LM2901AVQPWRQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901AVQ	Samples
LM2901QDRG4Q1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901Q1	Samples
LM2901QDRQ1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901Q1	Samples
LM2901QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901Q1	Samples
LM2901QPWRQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901Q1	Samples
LM2901VQDRG4Q1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901VQ1	Samples
LM2901VQDRQ1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901VQ1	Samples
LM2901VQPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901VQ	Samples
LM2901VQPWRQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901VQ	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

PACKAGE OPTION ADDENDUM

www.ti.com 28-Apr-2021

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LM2901-Q1, LM2901AV-Q1, LM2901V-Q1:

Catalog: LM2901, LM2901AV, LM2901V

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

www.ti.com 9-Nov-2021

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

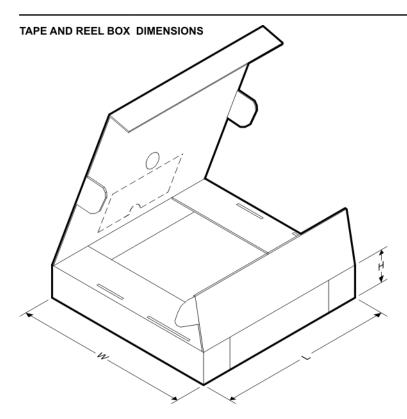
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2901AVQPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901AVQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901QPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901QPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901VQPWRG4Q1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901VQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 9-Nov-2021



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
LM2901AVQPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0	
LM2901AVQPWRQ1	TSSOP	PW	14	2000	853.0	449.0	35.0	
LM2901QPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0	
LM2901QPWRQ1	TSSOP	PW	14	2000	853.0	449.0	35.0	
LM2901VQPWRG4Q1	TSSOP	PW	14	2000	367.0	367.0	35.0	
LM2901VQPWRQ1	TSSOP	PW	14	2000	853.0	449.0	35.0	

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2021, Texas Instruments Incorporated